

L Number	Hits	Search Text	DB	Time stamp
1	29	(wiring) same (electrodes or plug) same (polish\$3 or planariz\$3) same clean\$3	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:02
3	1		USPAT	2003/06/25 09:54
5	837	(wiring) and (electrodes or plug) and (polish\$3 or planariz\$3) and clean\$3 and (UV or ultraviolet or light or irradiated or irradiating)	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:00
6	21553	CMP or "chemical mechanical polishing"	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:01
7	237	((wiring) and (electrodes or plug) and (polish\$3 or planariz\$3) and clean\$3 and (UV or ultraviolet or light or irradiated or irradiating)) and (CMP or "chemical mechanical polishing")	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:01
8	227	((wiring) and (electrodes or plug) and (polish\$3 or planariz\$3) and clean\$3 and (UV or ultraviolet or light or irradiated or irradiating)) and (CMP or "chemical mechanical polishing")) and semiconductor	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:02
9	514	(wiring or interconnect or conductive) and (electrodes or plug) same (polish\$3 or planariz\$3) same clean\$3	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:03
10	6045	(wiring or interconnect or conductive) and (electrodes or plug) and (polish\$3 or planariz\$3) and clean\$3	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:04
11	3218	(wiring or interconnect or conductive) and (electrodes or plug) and (polish\$3 or planariz\$3) and clean\$3 and (UV or "ultra violet" or light)	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:06
12	3	(wiring or interconnect or conductive) same (electrodes or plug) same (polish\$3 or planariz\$3) same clean\$3 same (UV or "ultra violet" or light)	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:10
13	1473	(wiring or interconnect or conductive) same clean\$3 same (UV or "ultra violet" or light)	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:11
14	275	(wiring or interconnect) same clean\$3 same (UV or "ultra violet" or light)	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:12
15	85	((wiring or interconnect) same clean\$3 same (UV or "ultra violet" or light)) and semiconductor	USPAT; EPO; JPO; IBM_TDB	2003/06/25 10:12